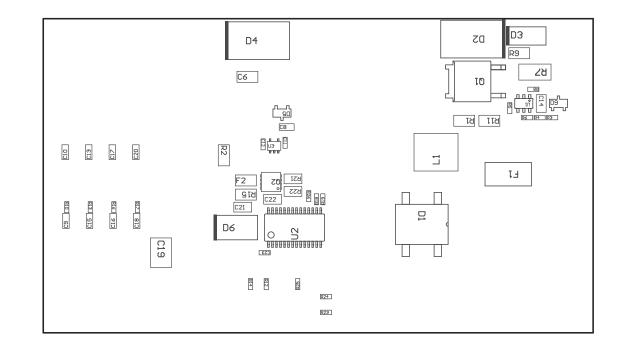


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP11069	REV: A	SVN REV:	Not In VersionControl		
	TID #:					
PLOT NAME = Top Assembly Drawing	GENERATED : 5/4/20	)15 4:43:49	PM	TEXAS INSTRUMENTS		



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP11069	REV: A	SVN REV	: Not In VersionControl	
	TID #: PMP11069				
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/4/20	)15 4:43:50	PM	TEXAS INSTRUMENTS	

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